

### Description

The AON7264E uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})},$  low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = 60V I<sub>D</sub> =40 A

 $R_{DS(ON)}$  < 15m $\Omega$  @ V<sub>GS</sub>=10V

### Application

Battery protection

Load switch

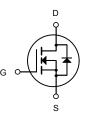
Uninterruptible power supply

#### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)		
AON7264E	DFN3X3-8L	40N06 XXYY	5000		
bsolute Maximum	⊓ Ratings (Tc=25℃unless c	otherwise noted)			
Symbol	Parameter		Rating	Units	
VDS	Drain-Source Vo	Itage	60	V	
VGS	Gate-Source Voltage		±20	V	
I₀@Tc=25°C	Continuous Drain Current	, V <sub>GS</sub> @ 10V <sup>1</sup>	V <sup>1</sup> 40		
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current	, V <sub>GS</sub> @ 10V <sup>1</sup>	0V <sup>1</sup> 20		
IDM	Pulsed Drain Cur	rrent <sup>2</sup>	<sup>2</sup> 150		
EAS	Single Pulse Avalanch	Single Pulse Avalanche Energy <sup>3</sup>		mJ	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissip	oation <sup>4</sup>	30		
TSTG	Storage Temperature	e Range	-55 to 150	°C	
TJ	Operating Junction Tempe	erature Range	-55 to 150	°C	
R <sub>0</sub> JA	Thermal Resistance Junc	tion-ambient <sup>1</sup>	62	°C/W	
R₀JC	Thermal Resistance Jur	nction-Case <sup>1</sup>	2.5	°C/W	







N-Channel MOSFET



# **Electrical Characteristics** (TJ=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units	
Off Charac	cteristic			-			
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	60	-	-	V	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V,	-	-	1.0	μA	
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±100	nA	
On Charac	teristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	1.0	1.6	2.5	V	
D	Static Drain-Source on-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	12	15		
$R_{\text{DS(on)}}$		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	-	15	20	mΩ	
Dynamic C	Characteristics						
Ciss	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	930	-	pF	
Coss	Output Capacitance		-	230	-	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	8	-	pF	
Qg	Total Gate Charge	V <sub>DS</sub> =30V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	22	-	nC	
Q <sub>gs</sub>	Gate-Source Charge		-	4.5	-	nC	
$Q_{gd}$	Gate-Drain("Miller") Charge	VGS-10V	-	3.5	-	nC	
Switching	Characteristics						
t <sub>d(on)</sub>	Turn-on Delay Time	$V_{DD}$ =30V, $I_{D}$ =20A, R <sub>G</sub> =1.6Ω, V <sub>GS</sub> =10V	-	4.5	-	ns	
tr	Turn-on Rise Time		-	2.7	-	ns	
t <sub>d(off)</sub>	Turn-off Delay Time		-	13.8	-	ns	
t <sub>f</sub>	Turn-off Fall Time		-	2.7	-	ns	
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings					
ls	Maximum Continuous Drain to Source Diode Forward Current		-	-	40	A	
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	150	Α	
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =30A	-	-	1.2	V	
trr	Body Diode Reverse Recovery Time	<b>T</b> 05*0	-	18	-	ns	
Qrr	Body Diode Reverse Recovery Charge	Tյ=25℃, I <sub>F</sub> =20A,dI/dt=100A/µs	-	12	-	nC	

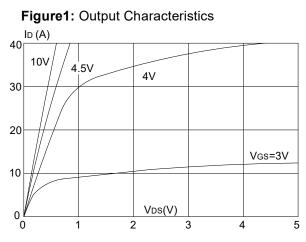
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T\_J=25  $^\circ \!\! C$  , V\_DD=30V, V\_G=10V, R\_G=25\Omega, L=0.5mH, I\_{AS}=12A

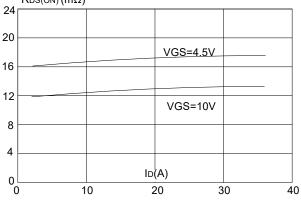
3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%

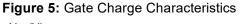


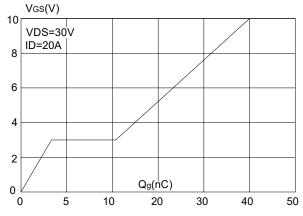
# **Typical Performance Characteristics**

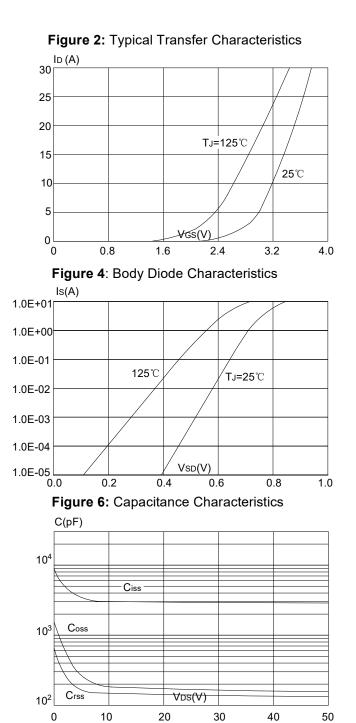


**Figure 3:**On-resistance vs. Drain Current RDS(ON) (mΩ)











**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature

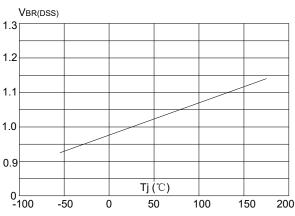
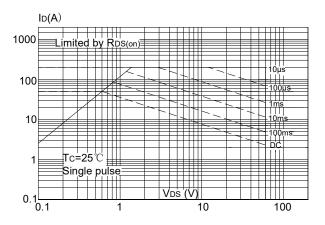
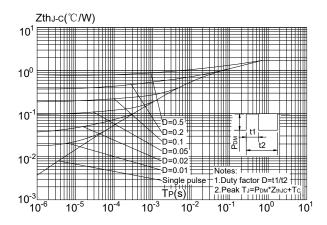


Figure 9: Maximum Safe Operating Area



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



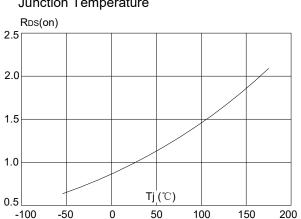
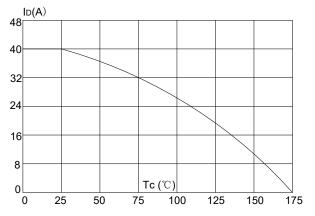
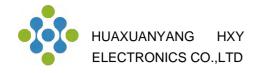


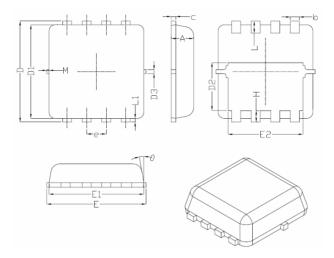
Figure 10: Maximum Continuous Drain Current vs. Case Temperature



**Figure 8:** Normalized on Resistance vs. Junction Temperature



# DFN3X3-8L Package Information



Symbol	Dimensions In Millimeters				
Symbol	Min.	Nom.	Max.		
A	0.70	0.75	0.80		
b	0.25	0.30	0.35		
С	0.10	0.15	0.25		
D	3.25	3.35	3.45		
D1	3.00	3.10	3.20		
D2	1.48	1.58	1.68		
D3	-	0.13	-		
E	3.20	3.30	3.40		
E1	3.00	3.15	3.20		
E2	2.39	2.49	2.59		
e	0.65BSC				
Н	0.30	0.39	0.50		
L	0.30	0.40	0.50		
L1	-	0.13	-		
М	*	*	0.15		
θ		10 <sup>°</sup>	12 <sup>°</sup>		



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